

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims

1. (Currently Amended) A process for producing a printed wiring board, comprising a step of depositing a base metal on at least one surface of an insulating film to form a base metal layer and depositing copper or a copper alloy on a surface of the base metal layer to form a conductive metal layer and a step of selectively removing a metal layer of a base film, which is formed through the above step, by etching to form a wiring pattern, wherein:

after the metal layer of the base film is selectively removed by etching to form a wiring pattern, microetching is carried out, and then, the base metal layer is treated with a treating liquid capable of dissolving and/or passivating the metal that forms the base metal layer an etching solution, which is capable of dissolving metal and has a function that it can passivate metal that is remaining in trace amounts, to dissolve and remove most of a metal that forms the base metal layer exposed between the wiring patterns and to passivate a trace amount of a residual metal which has not been dissolved by treatment with the etching solution.

2. (Original) The process for producing a printed wiring board as claimed in claim 1, wherein the base metal layer is formed from a metal containing nickel and/or chromium.

3. (Original) The process for producing a printed wiring board as claimed in claim 1, wherein the conductive metal layer is obtained by depositing copper or a copper alloy by plating.

4. (Original) The process for producing a printed wiring board as claimed in claim 1, wherein after the metal layer of the base film is selectively removed by etching to

form a wiring pattern, the surface of the wiring pattern formed by selectively etching the metal layer is subjected to pickling, and then the base metal layer is treated with a treating liquid capable of dissolving chromium and passivating an extremely slight amount of chromium which has not been dissolved.

5. (Withdrawn) A printed wiring board comprising an insulating film and a wiring pattern formed on at least one surface of the insulating film, said wiring pattern comprising a base metal layer formed on the insulating film surface and a conductive metal layer formed on a surface of the base metal layer, said base metal layer for forming the wiring pattern being protruded widthwise more than the conductive metal layer for forming the wiring pattern.

6. (Withdrawn) The printed wiring board as claimed in claim 5, wherein the base metal layer is formed from a metal containing one or both of nickel and chromium.

7. (Withdrawn) The printed wiring board as claimed in claim 5, wherein the conductive metal layer is formed from copper or a copper alloy.

8. (Withdrawn) The printed wiring board as claimed in claim 5, wherein at least a part of the surface of the wiring pattern composed of the base metal layer that is protruded in the width direction of the wiring pattern is passivated.

9. (Withdrawn) The printed wiring board as claimed in claim 5, wherein the conductive metal layer has almost the same shape as that of a masking pattern, and the wiring pattern and the insulating film are bonded by the base metal layer which is formed below the lower end of the wiring pattern composed of the conductive metal layer and around the wiring pattern and which is protruded widthwise from the conductive metal layer.

10. (Withdrawn) The printed wiring board as claimed in claim 5, wherein the base metal layer and the conductive metal layer are formed from metals or metal alloys having different properties from each other.

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11. (Withdrawn) A circuit device comprising the printed wiring board of claim 5 and an electronic component mounted thereon.